

BTA316X-600E 3Q Hi-Com Triac

Rev.03 - 25 September 2024

Product data sheet

1. General description

Planar passivated high commutation three quadrant triac in a TO220F "full pack" plastic package. The "series E" triac balances the requirements of commutation performance and gate sensitivity. The "sensitive gate" "series E" is intended for interfacing with low power drivers including microcontrollers.

2. Features and benefits

- 3Q technology for improved noise immunity
- Direct interfacing with low power drivers and microcontrollers
- Good immunity to false turn-on by dV/dt
- High commutation capability with sensitive gate
- High voltage capability
- Isolated mounting base package
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only

3. Applications

- Electronic thermostats
- High power motor controls e.g. washing machines and vacuum cleaners

4. Quick reference data

Symbol	Parameter	Conditions	Notes		Values	•	Unit
V _{DRM}	repetitive peak off-state voltage				600		V
I _{T(RMS)}	RMS on-state current	full sine wave; T _h ≤45 °C; <u>Fig. 1; Fig. 2; Fig. 3</u>			16		A
I _{TSM}	non-repetitive peak on- state current	full sine wave; T _{j(init)} = 25 °C; t _p = 20 ms; <u>Fig. 4; Fig. 5</u>			140		A
		full sine wave; $T_{j(init)}$ = 25 °C; t_p = 16.7 ms			150		А
Tj	junction temperature				125		°C
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
I _{GT}	gate trigger current	$V_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}; \text{ T2+ G+};$ T _j = 25 °C; <u>Fig. 7</u>		-	-	10	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{ T2+ G-};$ T _j = 25 °C; <u>Fig. 7</u>		-	-	10	mA
		V_{D} = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; Fig. 7		-	-	10	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>		-	-	15	mA
		I _T = 18 A; T _i = 25 °C; <u>Fig. 10</u>			1.3	1.5	V

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Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Dynamic	characteristics						
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T _j = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit		60	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	$V_D = 400 \text{ V}; \text{ T}_j = 125 \text{ °C}; \text{ I}_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{ V}/\mu\text{s}; \text{ (snubberless condition); gate open circuit}$		5	-	-	A/ms
		$V_D = 400 \text{ V}; \text{ T}_j = 125 \text{ °C}; \text{ I}_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 10 \text{ V}/\mu\text{s}; \text{ gate open circuit}$		8	-	-	A/ms
		$V_D = 400 \text{ V}; \text{ T}_j = 125 \text{ °C}; \text{ I}_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 1 \text{ V}/\mu s;$ gate open circuit		12	-	-	A/ms

5. Pinning information

Table 2. P	inning infor	mation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	mb	
2	T2	main terminal 2		T2-T1
3	G	gate		Sym051
mb	n.c	mounting base; isolated		symu51
			$\begin{array}{ccc} U & U & U \\ 1 & 2 & 3 \end{array}$	

6. Ordering information

Table 3. Ordering info	rmation					
Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BTA316X-600E	TO220F	BTA316X-600E,127	Tube	50	SOT186A	14-Nov-2013
BTA316X-600E/DG		BTA316X-600E/DG,127	Tube	50	SOT186A (Halogen free)	14-Nov-2013

7. Marking

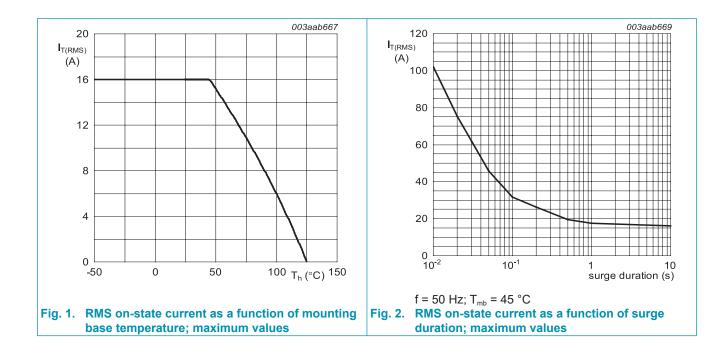
Table 4. Marking codes		
Type number	Marking codes	
BTA316X-600E	Assembly factory: d	Assembly factory: A
	BTA316X 600E PJdxxxx xx	BTA316X 600E PJAxxxx xx
BTA316X-600E/DG	BTA316X 600EDG PJdxxxx xx	BTA316X 600EDG PJAxxxx xx

8. Limiting values

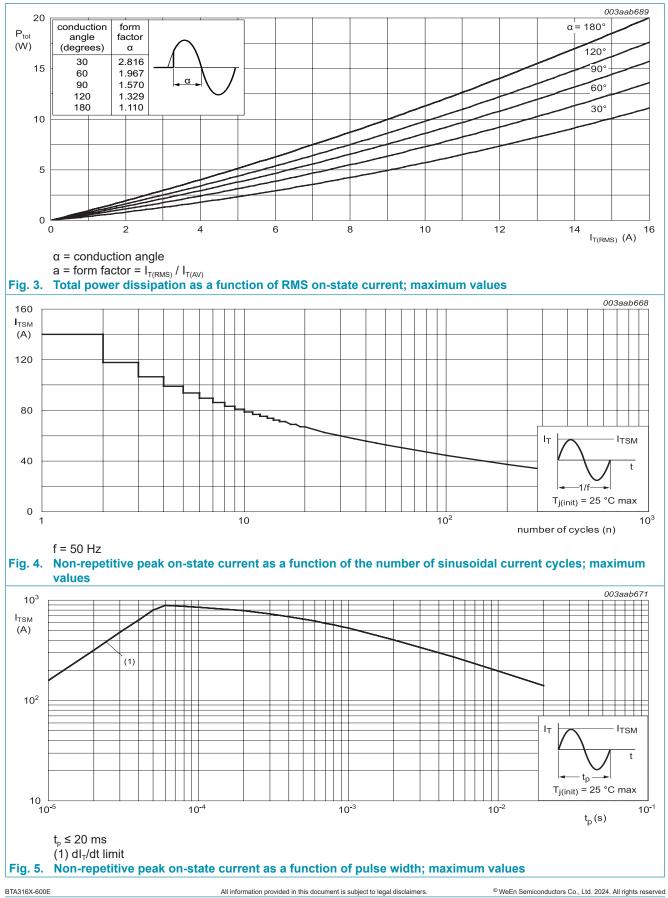
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{DRM}	repetitive peak off-state voltage			600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; T _h ≤ 45 °C; <u>Fig. 1; Fig. 2; Fig. 3</u>		16	A
I _{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)}$ = 25 °C; t_p = 20 ms; Fig 4; Fig 5		140	A
		full sine wave; $T_{j(init)}$ = 25 °C; t_p = 16.7 ms		150	А
l ² t	I ² t for fusing	t _p = 10 ms; SIN		98	A ² s
dl _T /dt	rate of rise of on-state current	I _G = 0.2 A		100	A/µs
I _{GM}	peak gate current			2	А
P_{GM}	peak gate power			5	W
$P_{G(AV)}$	average gate power	over any 20 ms period		0.5	W
T _{stg}	storage temperature			-40 to 150	°C
Tj	junction temperature			125	°C

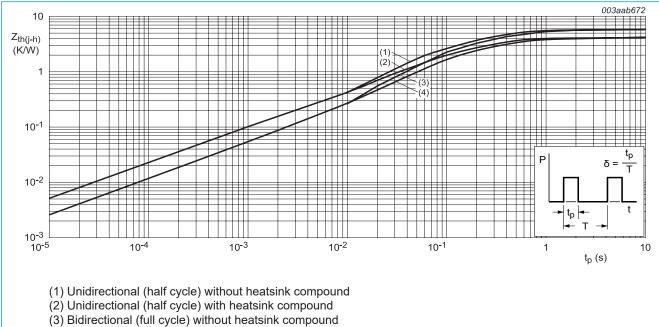


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9. Thermal characteristics

Table 6. Tl	hermal characteristics						
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
$R_{\text{th(j-h)}}$	thermal resistance from junction to heatsink	full cycle or half cycle; with heatsink compound; Fig 6		-	-	4	K/W
		full cycle or half cycle; without heatsink compound; Fig 6		-	-	5.5	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient	in free air		-	55	-	K/W



(4) Bidirectional (full cycle) with heatsink compound

Fig. 6. Transient thermal impedance from junction to heatsink as a function of pulse duration

10. Isolation characteristics

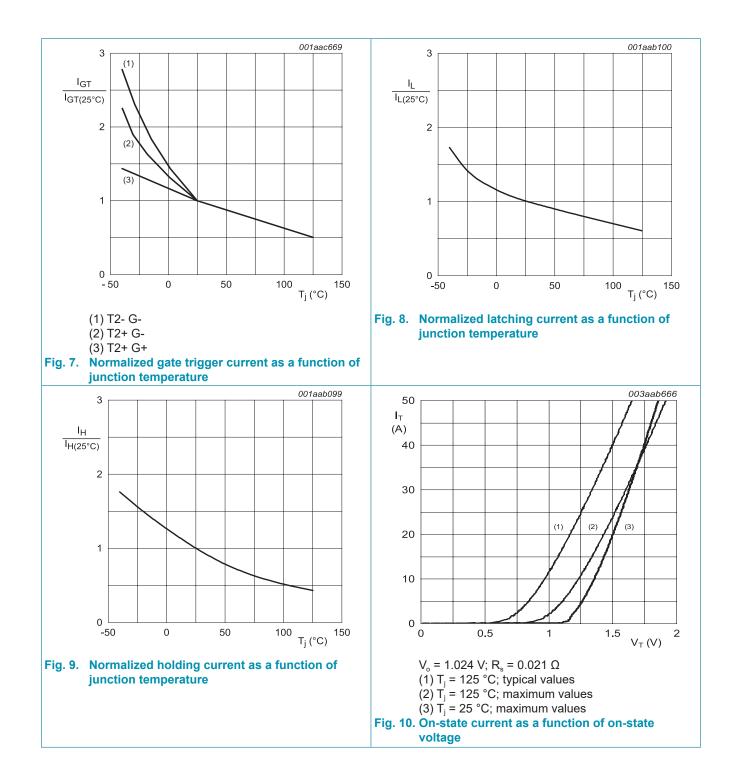
Table 7. Is	olation characteristics						
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
$V_{\text{isol}(\text{RMS})}$	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz \leq f \leq 60 Hz; RH \leq 65 %; T _h = 25 °C		-	-	2500	V
C_{isol}	isolation capacitance	from main terminal 2 to external heatsink; f = 1 MHz; T_h = 25 °C		-	10	-	pF

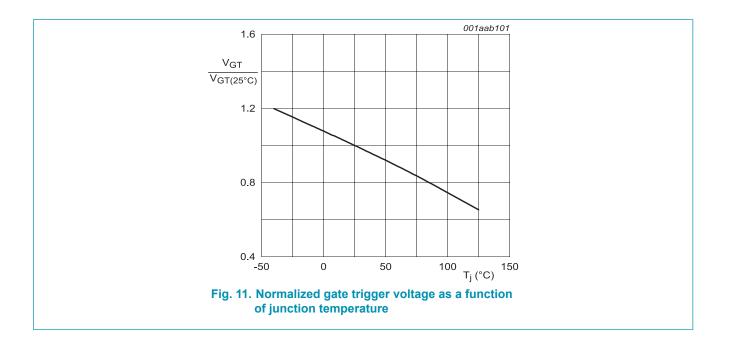
11. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	aracteristics				·		
I _{GT}	gate trigger current	$V_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}; \text{ T2+ G+};$ T _j = 25 °C; <u>Fig. 7</u>		-	-	10	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 7</u>		-	-	10	mA
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 7</u>		-	-	10	mA
l	latching current	$V_{D} = 12 \text{ V}; \text{ I}_{G} = 0.1 \text{ A}; \text{ T2+ G+};$ T _j = 25 °C; Fig. 8		-	-	25	mA
		V _D = 12 V; I _G = 0.1 A; T2+ G-; T _j = 25 °C; <u>Fig. 8</u>		-	-	30	mA
		V _D = 12 V; I _G = 0.1 A; T2- G-; T _j = 25 °C; <u>Fig. 8</u>		-	-	30	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>		-	-	15	mA
V _T	on-state voltage	I _T = 18 A; T _j = 25 °C; <u>Fig. 10</u>		-	1.3	1.5	V
V _{gt}	gate trigger voltage	$V_{D} = 12 \text{ V}; \text{ I}_{T} = 0.1 \text{ A}; \text{ T}_{j} = 25 \text{ °C};$ Fig. 11		-	0.8	1	V
		V _D = 400 V; I _T = 0.1 A; T _j = 125 °C		0.25	0.4	-	V
I _D	off-state current	V _D = 600 V; T _j = 125 °C		-	0.1	0.5	mA
Dynamic	characteristics						
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit		60	-	-	V/µs
dl _{com} /dt	rate of change of commutating current	$V_{D} = 400 \text{ V}; \text{ T}_{j} = 125 \text{ °C}; \text{ I}_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 20 \text{ V/}\mu\text{s}; \text{ (snubberless condition); gate open circuit}$		5	-	-	A/ms
		V_{D} = 400 V; T _j = 125 °C; I _{T(RMS)} = 16 A; dV _{com} /dt = 10 V/µs; gate open circuit		8	-	-	A/ms
		V_D = 400 V; T _j = 125 °C; I _{T(RMS)} = 16 A; dV _{com} /dt = 1 V/µs; gate open circuit		12	-	-	A/ms

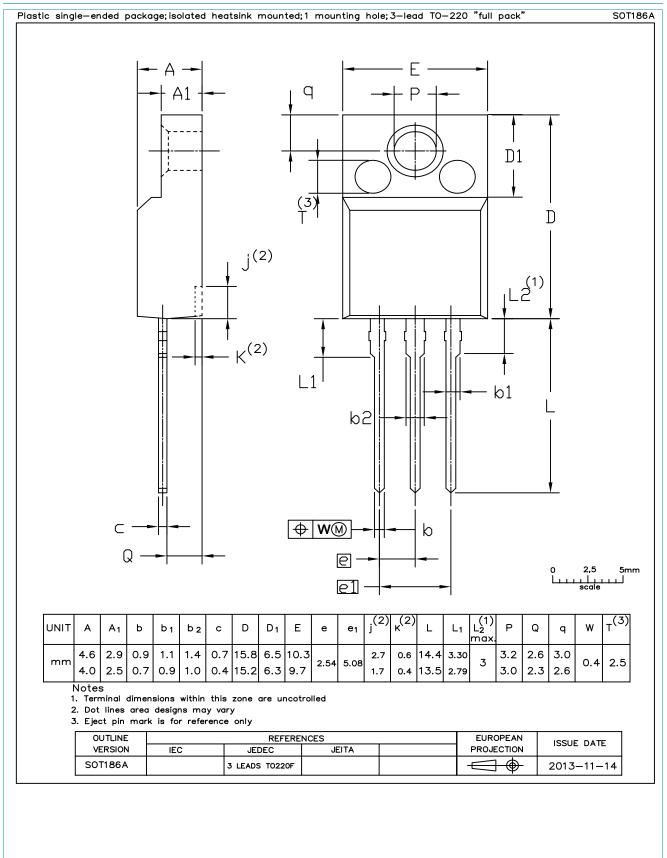
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12. Package outline



13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

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For more information, please visit: http://www.ween-semi.com

For sales office addresses, please send an email to: salesaddresses@ween-semi.com Date of release: 25 September 2024